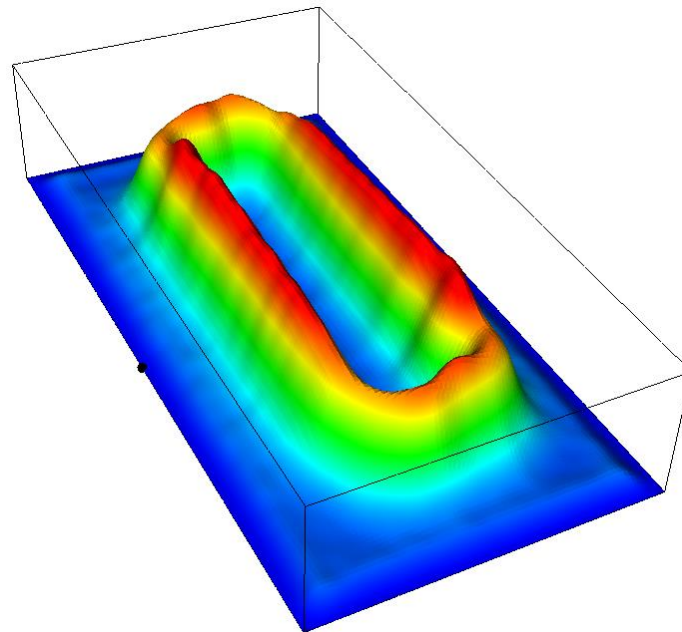


— CASE EXAMPLE —

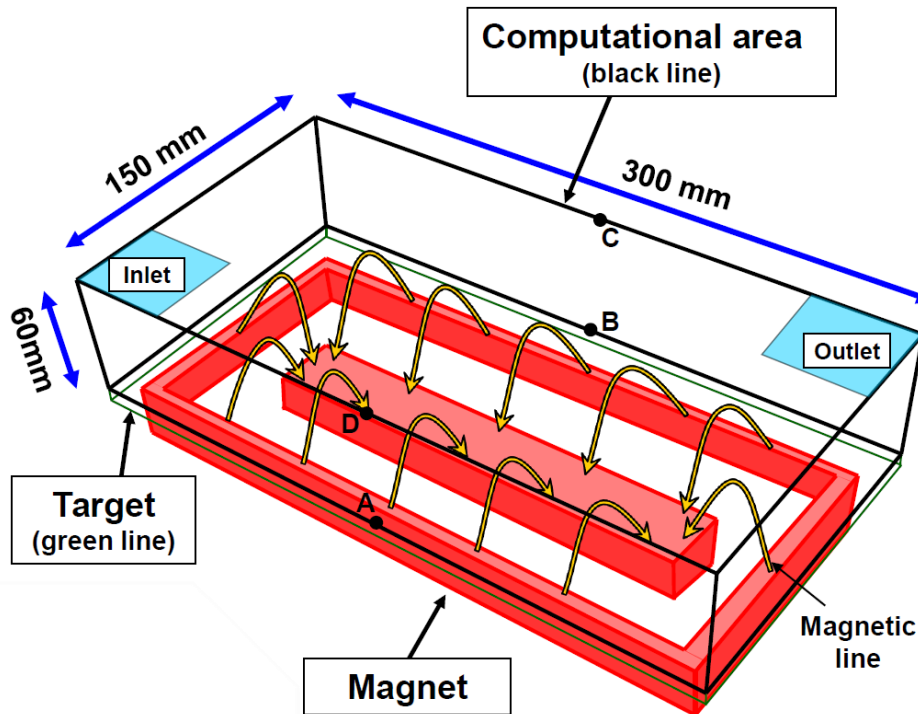
DC Magnetron Sputtering (3D Simulation)



Model

Cu Sputtered by Ar Plasma

3D Model

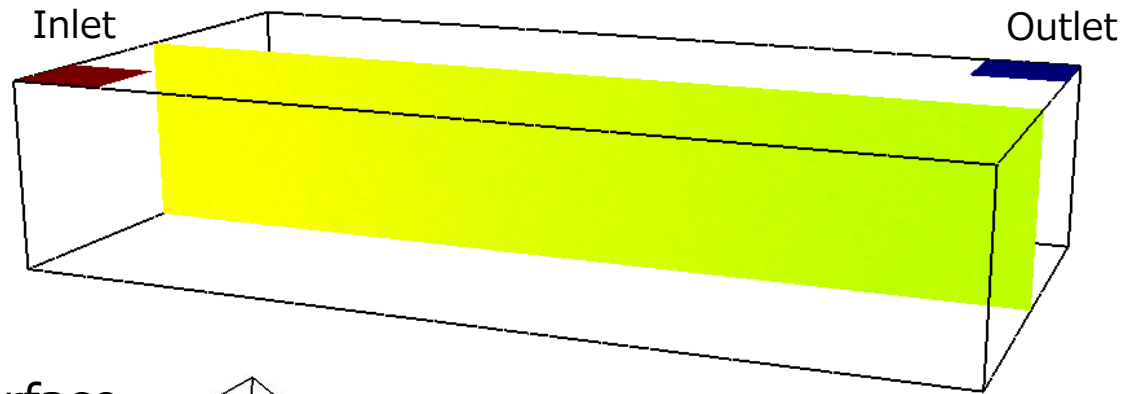


Gas Inlet		Ar 1.0 Pa
Gas Outlet		0.4 Pa
Magnet		Ferrite
Target	Material	Cu
	Voltage	DC -400 V
	SEY*	0.1
Target-Substrate Distance		60 mm

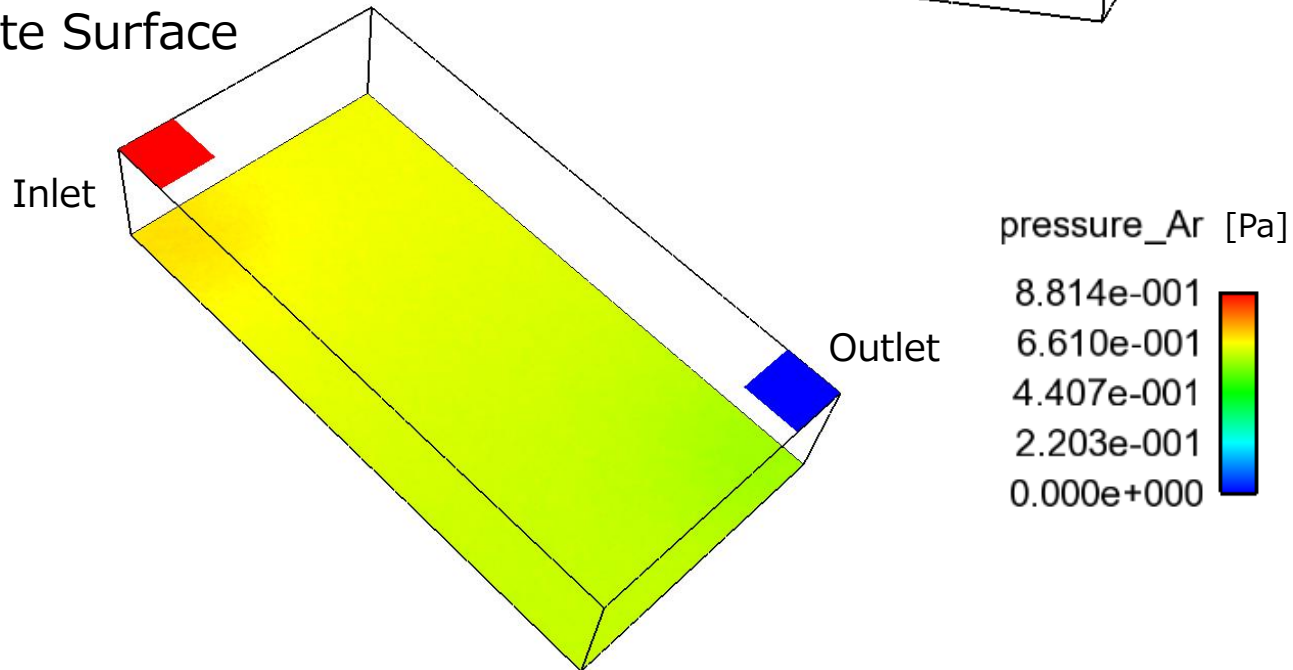
Upper surface: Substrate
 Under surface: Target (Cu)
 Side: Wall

➤ Substrate and walls are earthed.

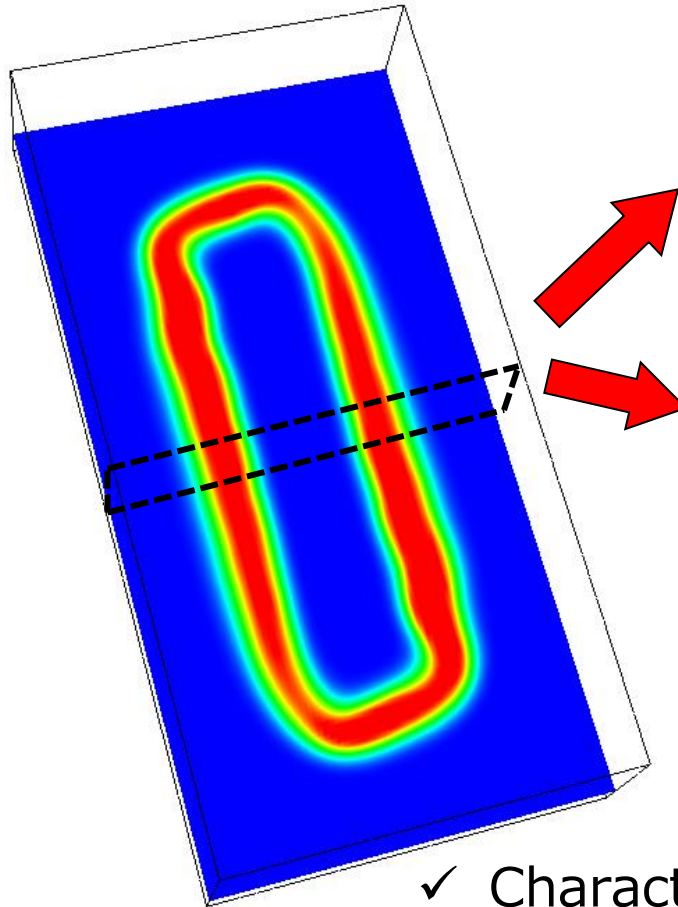
In Domain



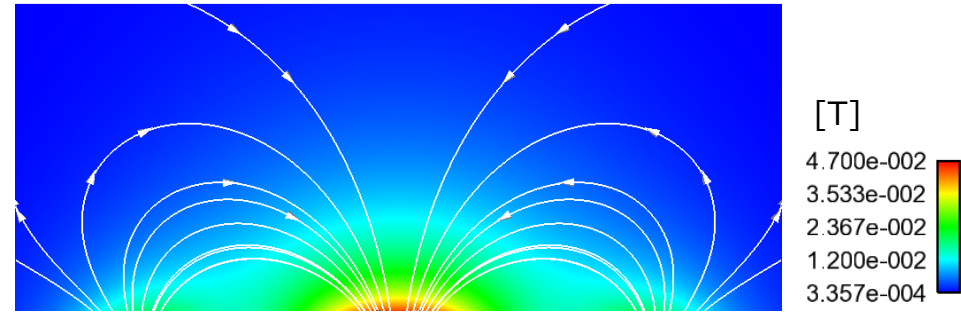
On Substrate Surface



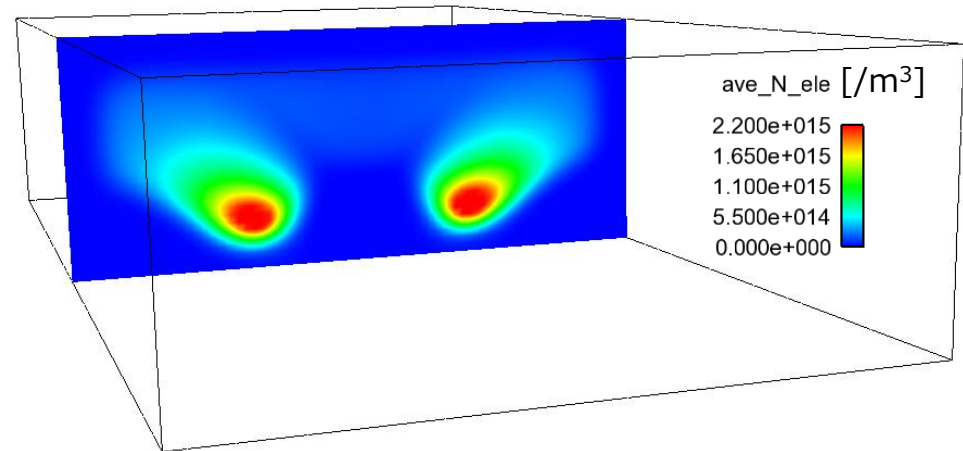
Electron Density on transverse plane



Magnetic Flux Density on longitudinal plane

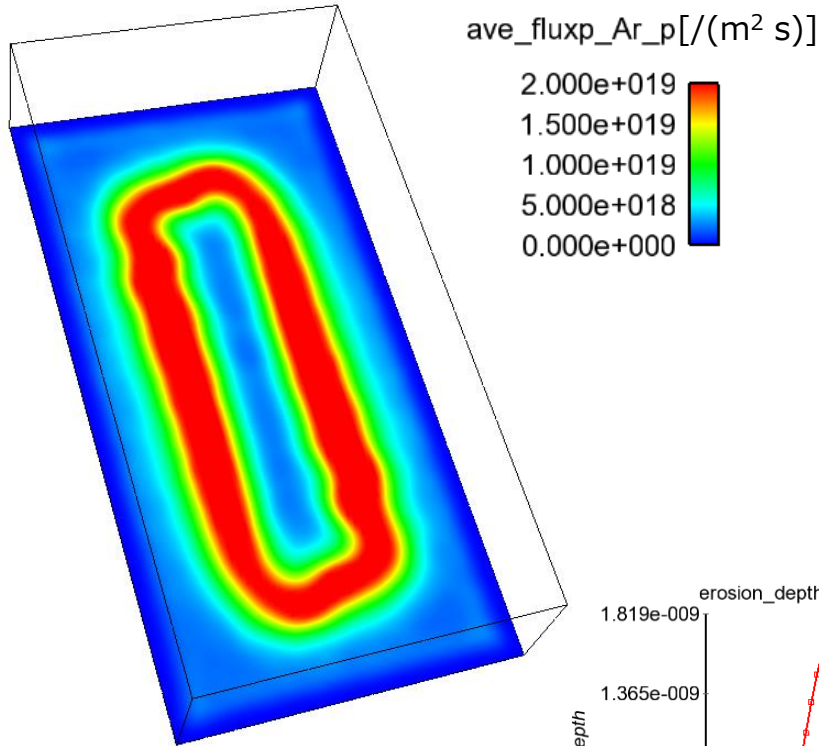


Electron Density on longitudinal plane

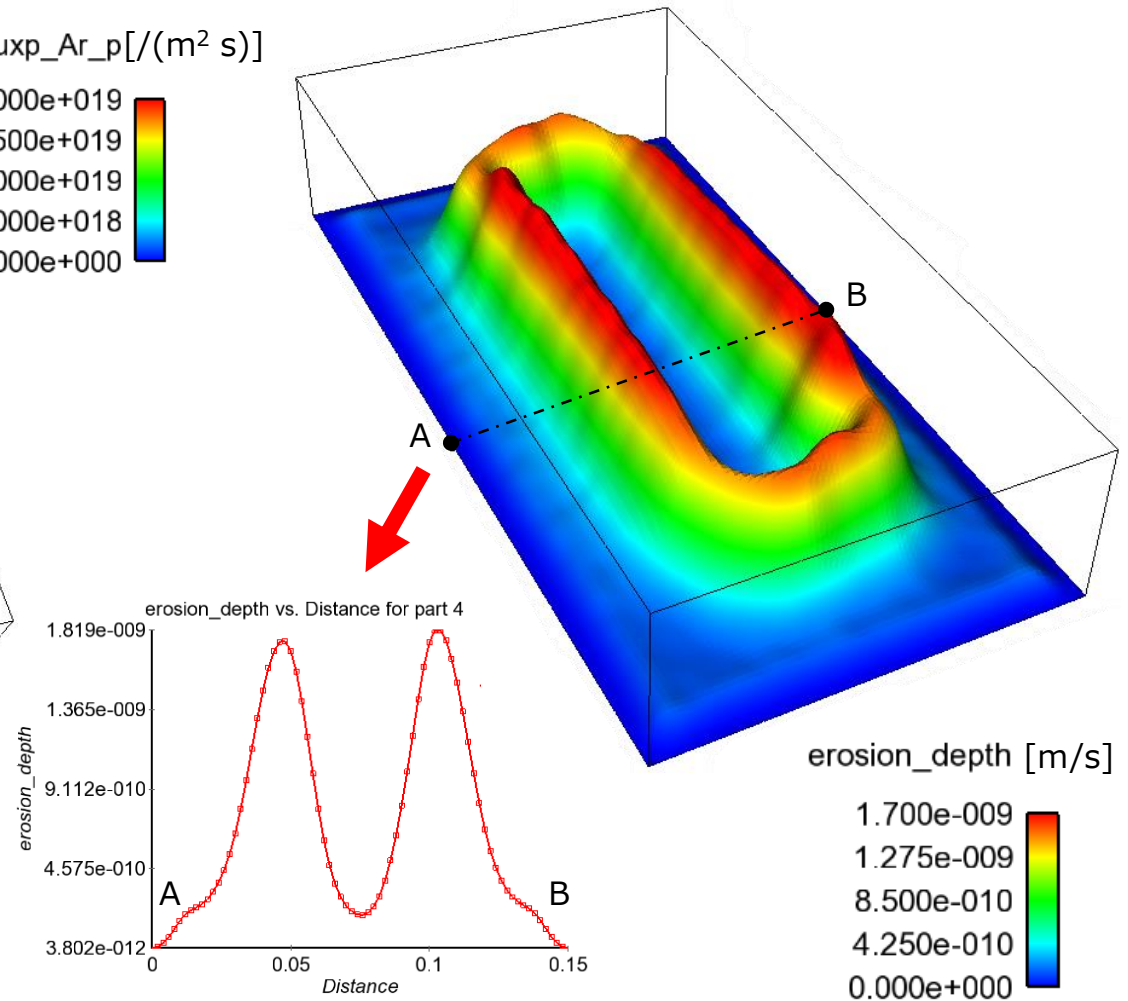


✓ Characteristic phenomena like **Cross-Corner Effect** are simulatable. [Q. H. Fan et. al., 2003]

Ion Flux on target



Cu Erosion Rate on target



Deposition

Cu Deposition Rate on surface

